

May. 12. 2005 3:40AM

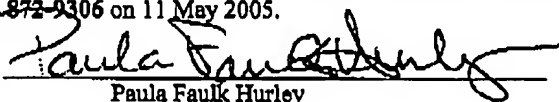
No. 0175 P. 1

Application No. 10/632,550  
Attorney Docket: CPAC 1017-7 D5

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I hereby certify that this correspondence is being sent by facsimile to:  
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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Marcos Karnezos	Attorney Docket No.: CPAC 1017-7 D5
Application No.: 10/632,550	Examiner: Mai-Huong Tran
Filed: 02 August 2003	Group: 2811
Title: Semiconductor Multi-Package Module Including Stacked-Die Package And Having Wire Bond Interconnect Between Stacked Packages	Confirmation No.: 2570
	Customer No. 22470

**INFORMATION DISCLOSURE STATEMENT AFTER ALLOWANCE**

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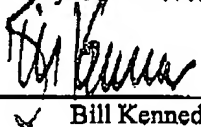
Sir:

Applicants submit the below-listed documents to be placed in the file:

- Takahashi et al., U. S. Patent No. 6,025,648 issued 15 February 2000 for "Shock Resistant Semiconductor Device and Method for Producing Same".

Respectfully submitted,  
Haynes Beffel & Wolfeld LLP

By:

 *By No. 33,407*  
✓ Bill Kennedy, Reg. No. 33,407

Date: 11 May 2005

Bill Kennedy  
Haynes Beffel & Wolfeld LLP  
P.O. Box 366  
Half Moon Bay, CA 94019  
Ph. (650) 712-0340  
Fax (650) 712-0263